Title (en)

HALOGEN-FREE RESIN COMPOSITION AND USE THEREOF

Title (de)

HALOGENFREIE HARZZUSAMMENSETZUNG VERWENDUNG DAVON

Title (fr)

COMPOSITION DE RÉSINE NON HALOGÉNÉE ET SON UTILISATION

Publication

EP 3037479 A4 20170125 (EN)

Application

EP 14882285 A 20140321

Priority

- CN 201410051996 A 20140214
- CN 2014073846 W 20140321

Abstract (en)

[origin: EP3037479A1] The present invention relates to a halogen-free resin composition, a prepreg and a laminate prepared therefrom. The halogen-free resin composition comprises, based on the weight parts of organic solids, (A) from 40 to 80 parts by weight of allyl-modified benzoxazine resin, (B) from 10 to 20 parts by weight of hydrocarbon resin, (C) from 10 to 40 parts by weight of allyl-modified polyphenyl ether resin, (D) from 10 to 20 parts by weight of allyl-modified bismaleimide resin, (E) from 0.01 to 3 parts by weight of an initiator, (F) from 10 to 100 parts by weight of a filler and (G) from 0 to 80 parts by weight of a phosphorus-containing flame retardant. The prepreg and laminate prepared from the halogen-free resin composition have lower dielectric constant and dielectric loss tangent value, higher peel strength, high glass transition temperature, excellent thermal resistance and better flame retardant effect.

IPC 8 full level

C08L 79/04 (2006.01); **C08K 3/00** (2006.01); **C08K 5/49** (2006.01); **C08L 25/10** (2006.01); **C08L 71/12** (2006.01); **C08L 79/08** (2006.01)

CPC (source: CN EP US)

B32B 5/022 (2013.01 - EP US); **B32B 5/024** (2013.01 - EP US); **B32B 5/26** (2013.01 - EP US); **B32B 7/10** (2013.01 - EP US); **B32B 15/08** (2013.01 - CN); **B32B 15/098** (2013.01 - EP US); **B32B 15/14** (2013.01 - EP US); **B32B 15/18** (2013.01 - EP US); **B32B 15/20** (2013.01 - CN EP US); **B32B 27/28** (2013.01 - CN); **C08G 14/06** (2013.01 - EP US); **C08G 14/12** (2013.01 - EP US); **C08K 3/00** (2013.01 - US); **C08K 3/36** (2013.01 - EP US); **C08K 5/14** (2013.01 - EP US); **C08K 5/49** (2013.01 - US); **C08K 5/5399** (2013.01 - EP US); **C08L 9/06** (2013.01 - EP US); **C08L 25/10** (2013.01 - EP US); **C08L 71/12** (2013.01 - EP US); **C08L 71/126** (2013.01 - EP US); **C08L 79/04** (2013.01 - CN US); **C08L 79/085** (2013.01 - EP US); **C09D 179/04** (2013.01 - US); **C09J 161/34** (2013.01 - EP US); **H05K 1/0298** (2013.01 - US); **H05K 1/0373** (2013.01 - US); **H05K 1/09** (2013.01 - US); B32B 2260/021 (2013.01 - EP US); B32B 2260/023 (2013.01 - EP US); B32B 2260/046 (2013.01 - EP US); B32B 2262/10 (2013.01 - EP US); B32B 2262/101 (2013.01 - EP US); B32B 2264/102 (2013.01 - EP US); B32B 2307/204 (2013.01 - EP US); B32B 2307/306 (2013.01 - EP US); B32B 2307/732 (2013.01 - EP US); B32B 2457/08 (2013.01 - CN EP US); C08L 2201/02 (2013.01 - CN); C08L 2201/08 (2013.01 - CN); C08L 2201/22 (2013.01 - CN); C08L 2203/20 (2013.01 - CN); C08L 2205/02 (2013.01 - CN); C08L 2205/025 (2013.01 - CN); C08L 2205/035 (2013.01 - CN); H05K 2201/012 (2013.01 - US); H05K 2201/0355 (2013.01 - US)

C-Set (source: CN EP US)

CN

C08L 79/04 + **C08L 25/10** + **C08L 71/12** + **C08L 79/08** + **C08L 85/02** + **C08K 7/18**

EP US

C09J 161/34 + **C08K 3/36** + **C08K 5/14** + **C08K 5/5399** + **C08L 9/06** + **C08L 71/126** + **C08L 79/085**

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Designated extension state (EPC)

BA ME

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